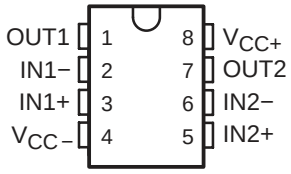
- **Single/Dual Power-Supply Operation**
- **High Output Current . . . 70 mA, V_{CC+} = 5 V**
- **Wide Operating Voltage . . . 3 V to 15 V (Single Supply)**
- **Ideal for Headphone Drivers**

D (SOIC), P (PDIP), OR PW (TSSOP) PACKAGE
(TOP VIEW)



description/ordering information

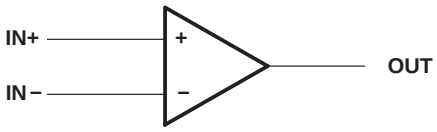
The TL3414A device is a dual operational amplifier that can be operated with single or dual power supplies. In addition to high gain and high output voltage swing, it is capable of driving a 70-mA load, making it ideally suited for simple, low-cost audio-amplifier applications, such as headphone amplifiers in DVD and CDRW applications.

ORDERING INFORMATION

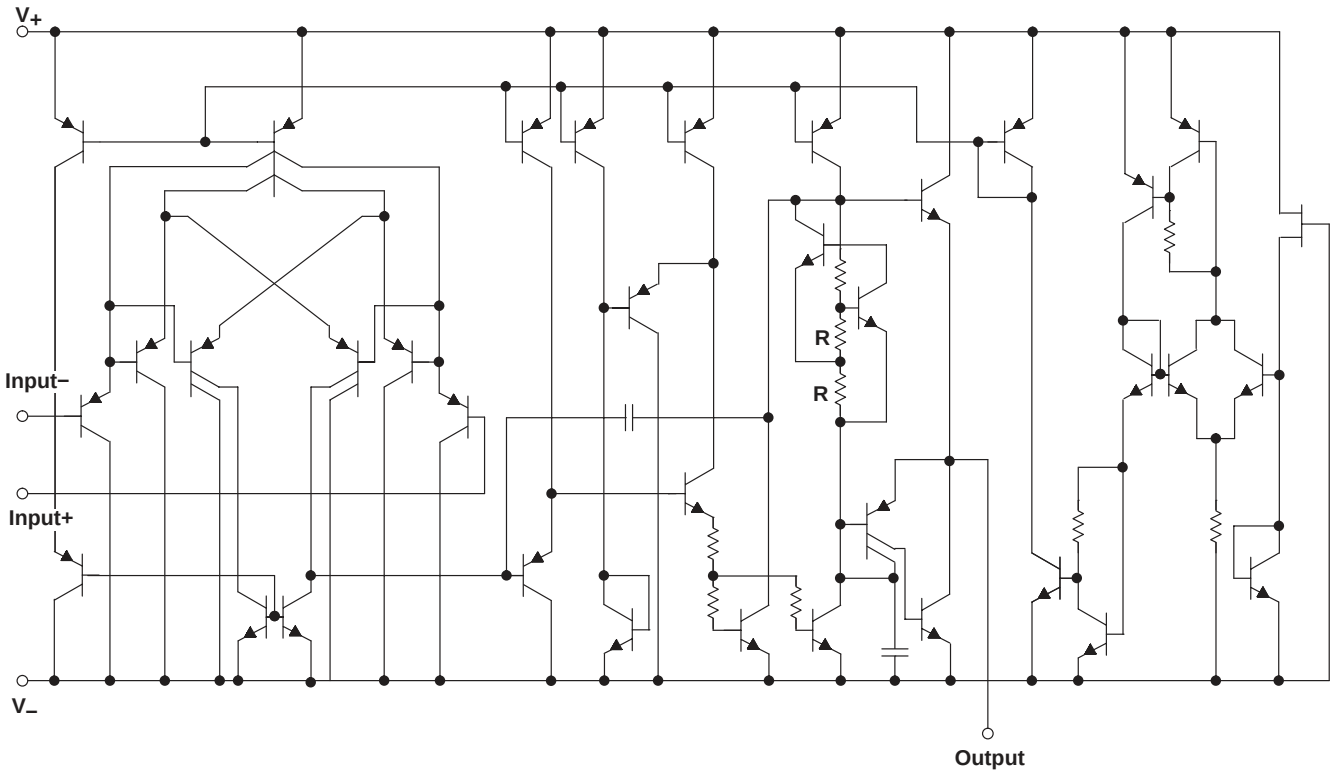
T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	PDIP (P)	Tube of 50	TL3414AIP	TL3414AIP
	SOIC (D)	Tube of 75	TL3414AID	Z3414A
		Reel of 2500	TL3414AIDR	
	TSSOP (PW)	Tube of 150	TL3414AIPW	Z3414A
		Reel of 2000	TL3414AIPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (each amplifier)



simplified schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC+} (single supply)	15 V
Supply voltage, V_{CC-} (single supply)	0 V
Supply voltage, V_{CC+} (dual supply)	7.5 V
Supply voltage, V_{CC-} (dual supply)	−7.5 V
Supply voltage, (V_{CC-} to V_{CC+})	15 V
Input voltage, either input (see Note 1)	V_{CC-} or V_{CC+}
Input current (see Note 2)	±10 mA
Duration of output short circuit (see Note 3)	Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5): D package	97°C/W
P package	85°C/W
PW package	149°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	−40°C to 125°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:
1. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
2. Excessive input current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
3. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
V_{CC}	Supply voltage (single supply)	3	15	V
V_{CC+}	Supply voltage (dual supply)	1.5	7.5	V
V_{CC-}	Supply voltage (dual supply)	−1.5	−7.5	V
V_{ID}	Differential input voltage		15	V
V_I	Input voltage	−0.3	15	V
T_A	Operating free-air temperature range	−40	85	°C

DC electrical characteristics, V_{CC+} = 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	R_S = 0 Ω		2	5	mV
I_{IO}	Input offset current			15	100	nA
I_{IB}	Input bias current			300	600	nA
A_{VD}	Large-signal differential voltage amplification	R_L = 2 kΩ	77	100		dB
V_{ICR}	Common-mode input voltage range		V_{CC+} − 2 V			V
V_{OM}	Output voltage swing	R_L > 2 kΩ, V_{CC+} = 5 V	3.5			V
		I_O = 70 mA, V_{CC+} = 5 V	3.2			
CMRR	Common-mode rejection ratio		70	79		dB
k_{SVR}†	Supply-voltage rejection ratio		80	90		dB
I_{CC}	Supply current (all amplifiers)	R_L = open circuit (full temperature range)	3	4	6	mA

† Measured with $V_{CC\pm}$ differentially and simultaneously varied from 5 V to 8.6 V

AC electrical characteristics, V_{CC+} = 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain		0.83	V/μs
GBW	Gain bandwidth product		1.1	MHz
V_n	Equivalent input noise voltage	f = 1 kHz	18	nV/√Hz

DC electrical characteristics, V_{CC+} = 8.6 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	R_S = 0 Ω		2	5	mV
I_{IO}	Input offset current			15	100	nA
I_{IB}	Input bias current			300	600	nA
A_{VD}	Large-signal differential voltage amplification	R_L = 2 kΩ	88	105		dB
V_{ICR}	Common-mode input voltage range		V_{CC+} − 2 V			V
V_{OM}	Output voltage swing	R_L > 2 kΩ, V_{CC+} = 8.6 V	7			V
		I_O = 70 mA, V_{CC+} = 8.6 V	6.7			
CMRR	Common-mode rejection ratio		80	90		dB
k_{SVR}†	Supply-voltage rejection ratio		80	90		dB
I_{CC}	Supply current (all amplifiers)	R_L = open circuit (full temperature range)	3	4	6	mA

† Measured with $V_{CC\pm}$ differentially and simultaneously varied from 5 V to 8.6 V

AC electrical characteristics, V_{CC+} = 8.6 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain		1.3	V/μs
GBW	Gain bandwidth product		2	MHz
V_n	Equivalent input noise voltage	f = 1 kHz	18	nV/√Hz

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL3414AID	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A	Samples
TL3414AIDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A	Samples
TL3414AIDRE4	LIFEBUY	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A	
TL3414AIPW	ACTIVE	TSSOP	PW	8	150	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A	Samples
TL3414AIPWR	ACTIVE	TSSOP	PW	8	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

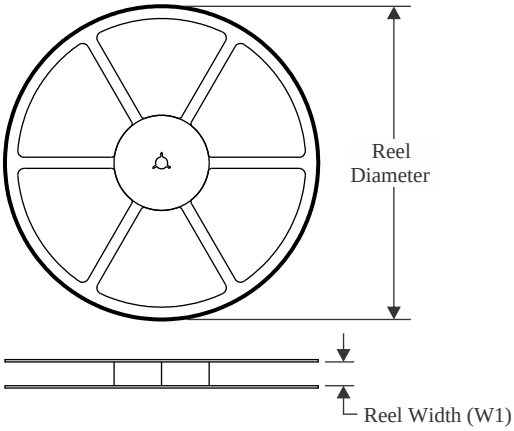
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals.
TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

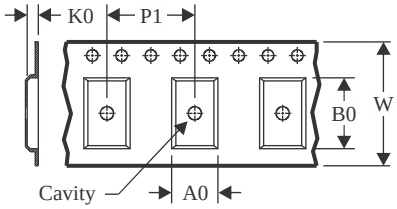
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

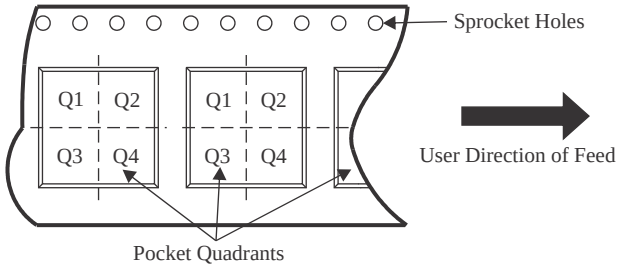


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

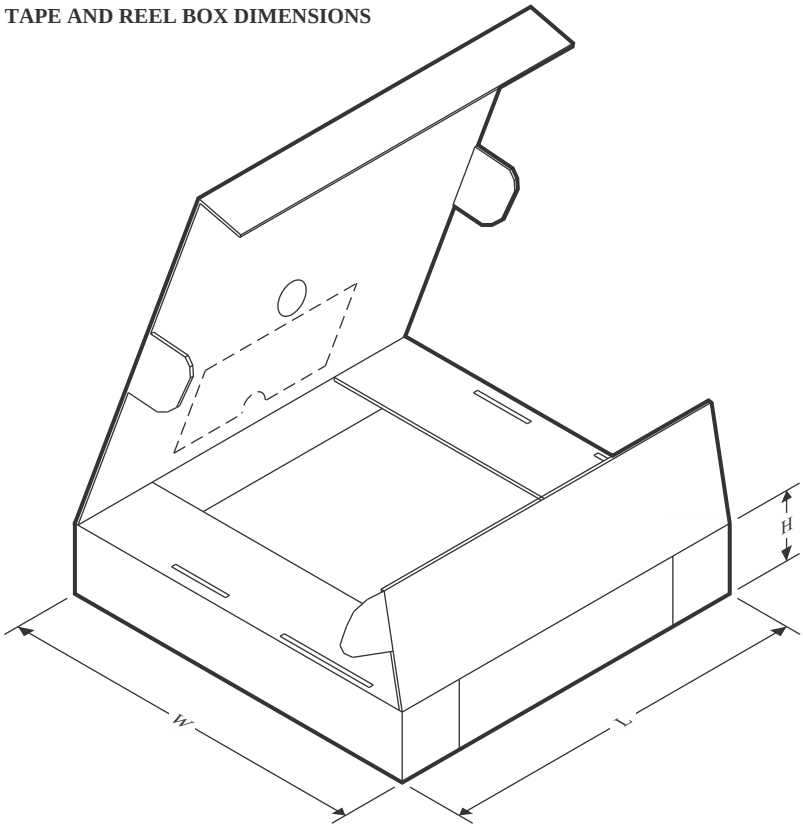
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3414AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3414AIPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

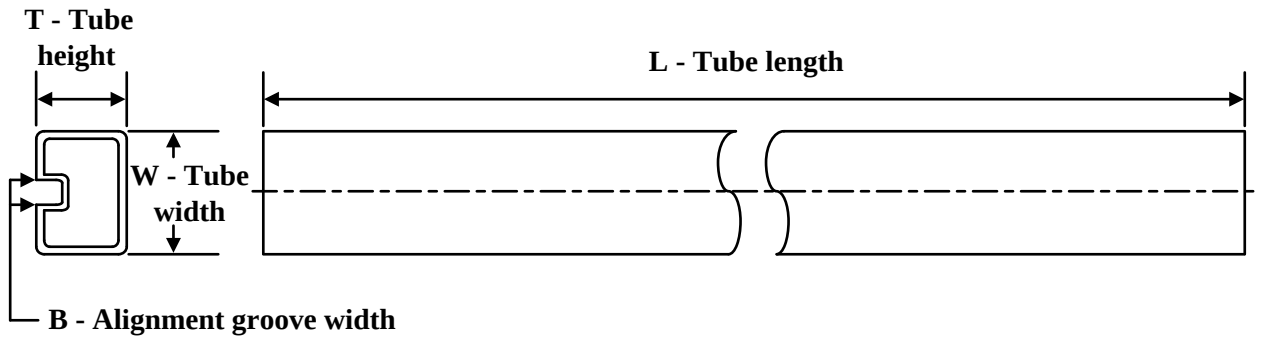
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

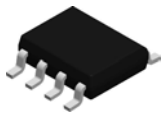
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3414AIDR	SOIC	D	8	2500	340.5	336.1	25.0
TL3414AIPWR	TSSOP	PW	8	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL3414AID	D	SOIC	8	75	507	8	3940	4.32
TL3414AIPW	PW	TSSOP	8	150	530	10.2	3600	3.5

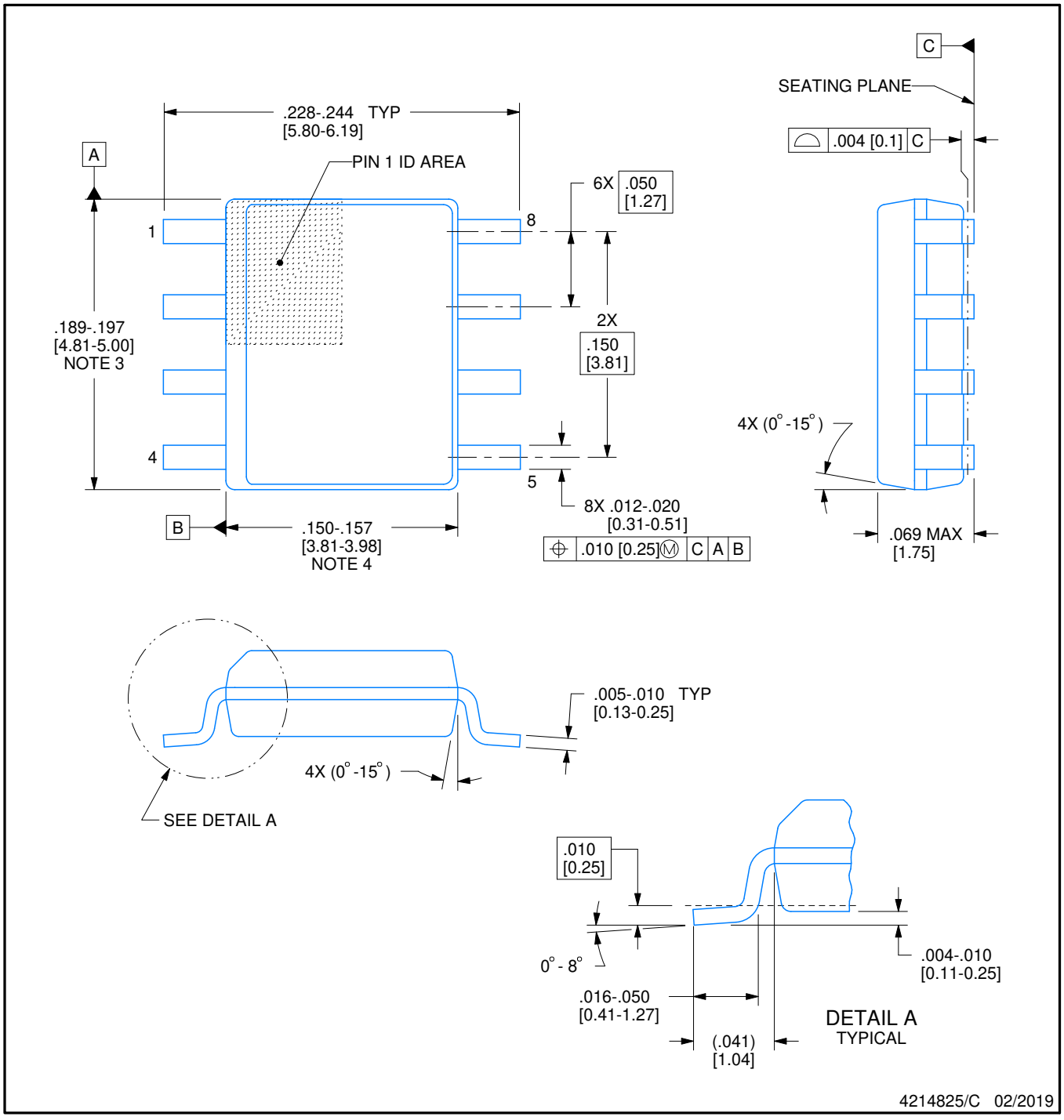


PACKAGE OUTLINE

D0008A

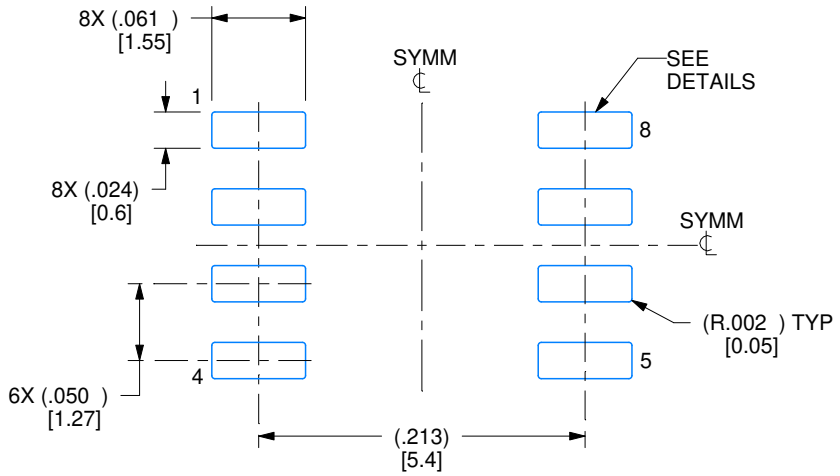
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

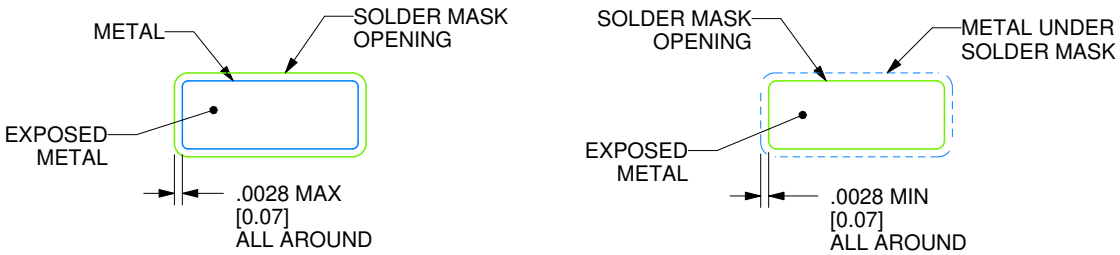


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

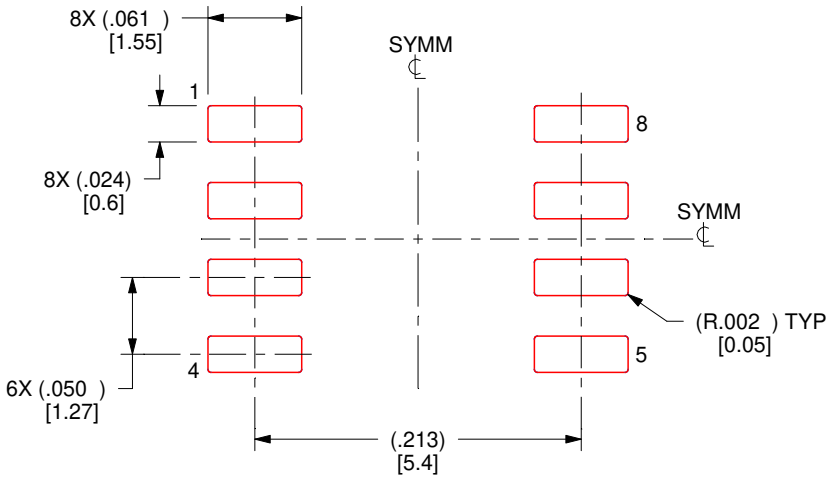
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

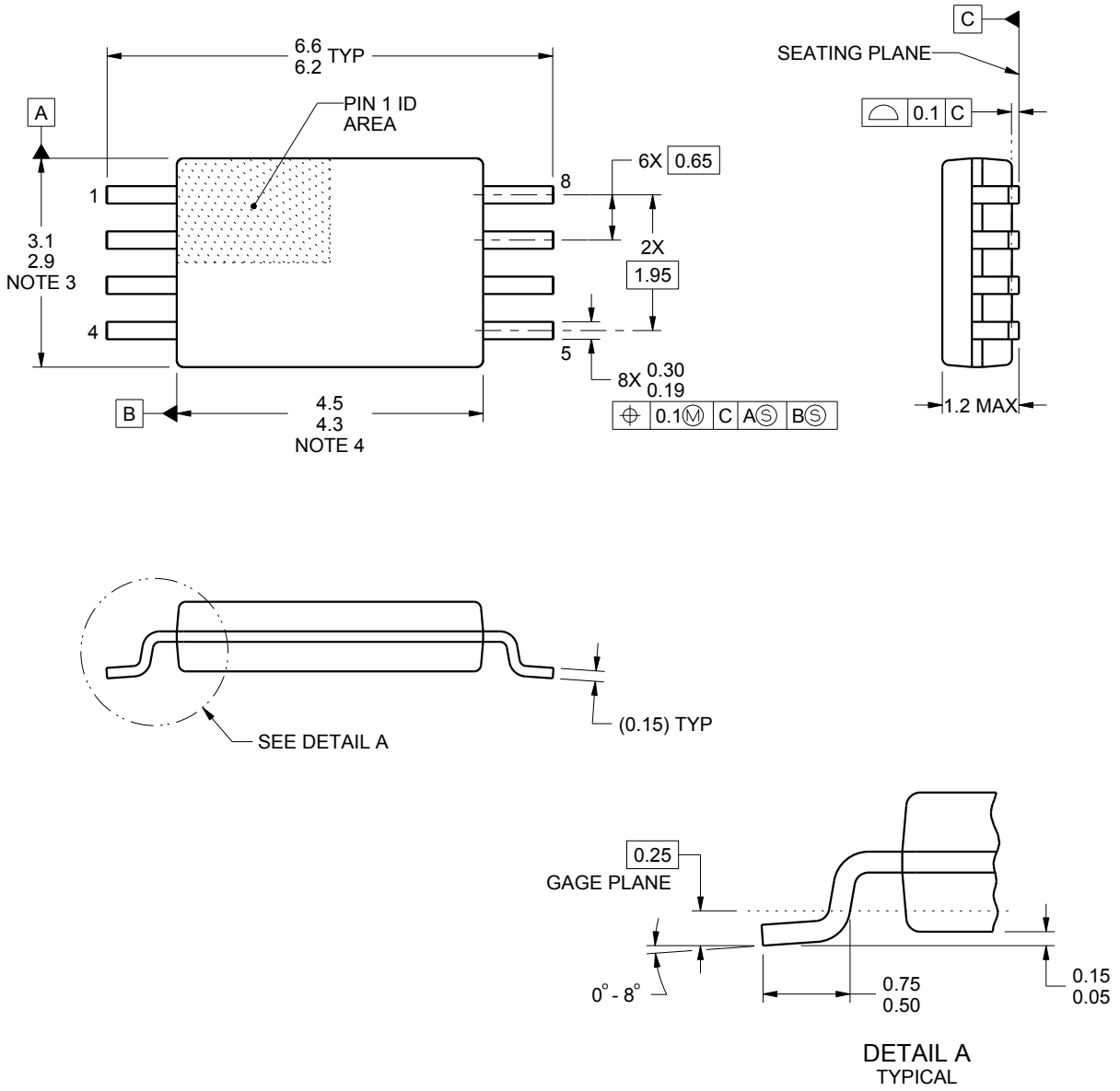
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0008A

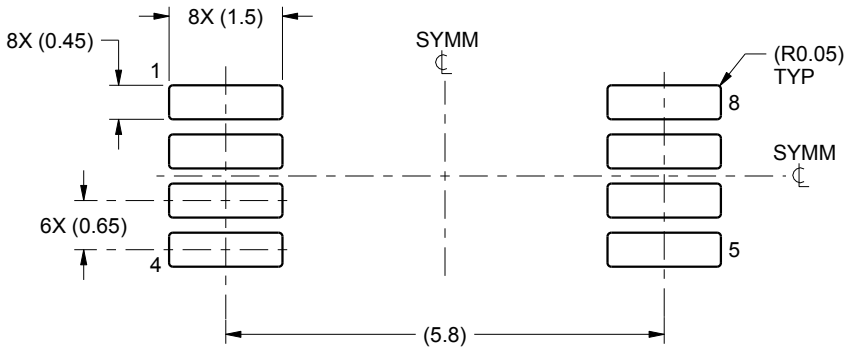
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

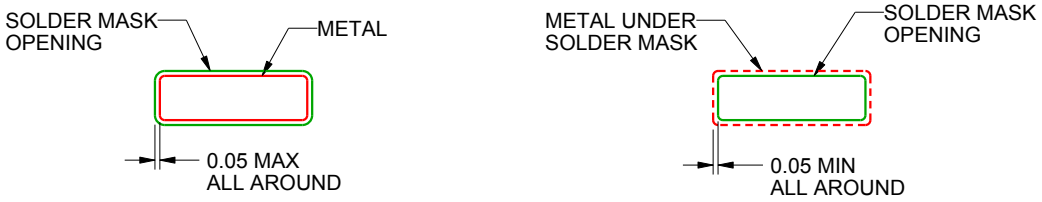


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.



LAND PATTERN EXAMPLE
SCALE:10X

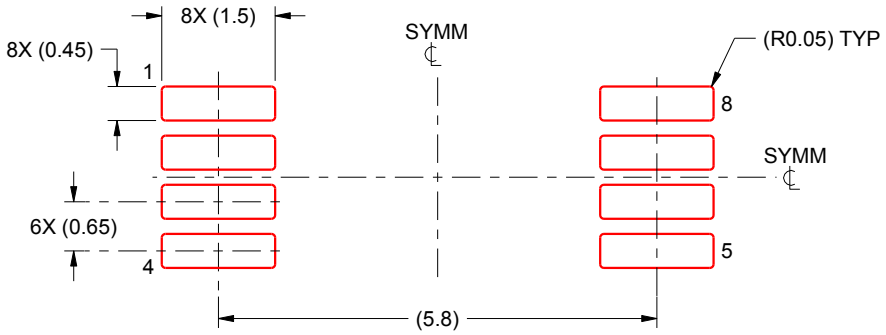


SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265